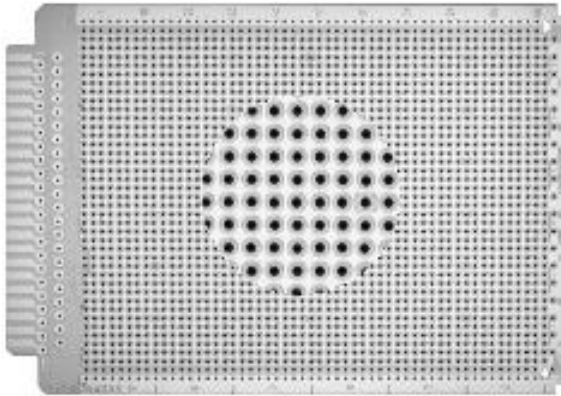


3662

4.5" x 6.5"

Circuit Pattern: Contacts Only
Contacts: 22/44 @ .156 Ctrs, Ni/Gold
Width/Thick: 6.50"/.062"
Height: 4.50"
16-Pin DIP Capacity: 50
Material: CEM-1
Wire-Wrap Terminals: T44, T46, T49, T68
Wire-Wrap Socket Pins: R32
Solder Connector: R644
Extender: 3690
Rec. Card Cage: Series 13
Wire-Wrap Connector: R644-3
Hole Diameter: .042"

- Unrestricted component placement over entire board surface
- Layout paper and instructions included
- Row and column legend provided

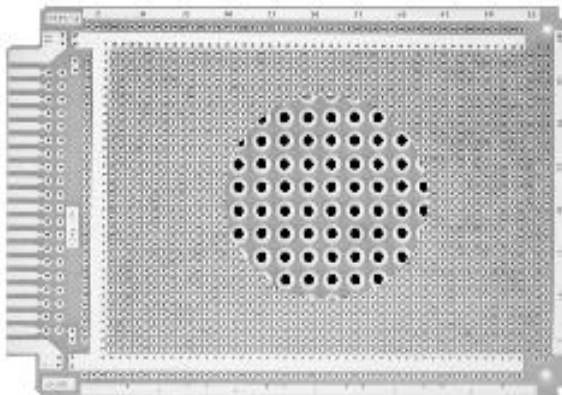


3662A6

4.5" x 6.5"

Circuit Pattern: Ground Plane
Contacts: 22/44 @ .156" Ctrs, Ni/Gold
Width/Thick: 6.50"/.062"
Height: 4.50"
16-Pin DIP Capacity: 90
Material: CEM-1
Wire-Wrap Terminals: T44, T46, T49, T68
Wire-Wrap Socket Pins: R32
Solder Connector: R644
Extender: 3690
Rec. Card Cage: Series 13
Wire-Wrap Connector: R644-3
Hole Diameter: .042"

- 0.085" diameter clearance area around holes
- Ground plane on component side; wiring side has contacts only
- To commit wire-wrap pins to ground planes, use Vector T124 solder washers, available separately
- Plane surface is solder-coated for user convenience
- Layout paper and instructions included
- Row and column legend provided

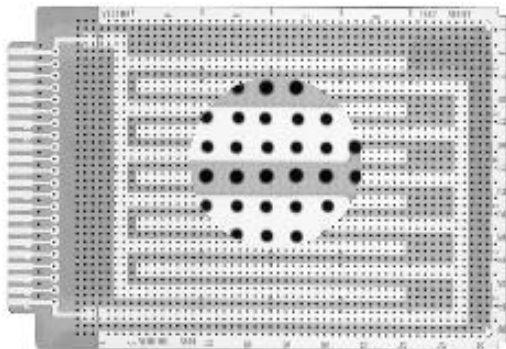


3662-9

4.5" x 6.5"

Circuit Pattern: Pad-Per-Hole
Contacts: 22/44 @ .156" Ctrs, Ni/Gold
Width/Thick: 6.50"/.062"
Height: 4.50"
16-Pin DIP Capacity: 48
Material: FR4 Epoxy Glass
Wire-Wrap Terminals: T44, T46, T49, T68
Wire-Wrap Socket Pins: R32
Solder Connector: R644
Extender: 3690
Rec. Card Cage: Series 13
Wire-Wrap Connector: R644-3
Hole Diameter: .042"

- 0.080" diameter, isolated solder pad around holes, both sides
- Pad and bus surfaces solder-coated for quick, convenient soldering
- Row and column legends provided
- Layout paper and instructions included



3682-2

4.5" x 6.5"

Circuit Pattern: Interleaved Buses
Contacts: 22/44 @ .156" Ctrs, Ni/Gold
Width/Thick: 6.50"/.062"
Height: 4.50"
16-Pin DIP Capacity: 24
Material: CEM-1
Wire-Wrap Terminals: T44, T46, T49, T68
Wire-Wrap Socket Pins: R32
Solder Connector: R644
Extender: 3690
Rec. Card Cage: Series 13
Wire-Wrap Connector: R644-3
Hole Diameter: .042"

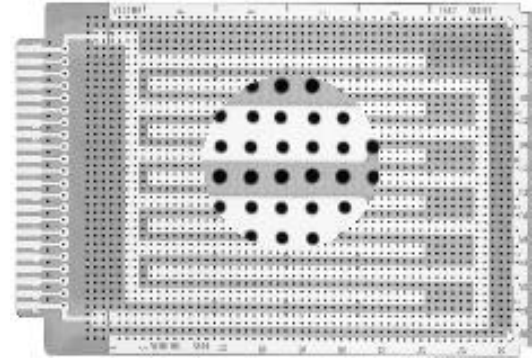
- Bus pattern on wiring side, solder-coated for user convenience
- Bus outline traced on component side to facilitate component placement
- Mounts DIPs with 0.3", 0.4" and 0.9" lead spacing
- Unclad test point area at top of board
- Layout paper and instructions included
- Row and column legends provided

Note: Same as 3682-4 but without Ground Plane

3682-4 4.5" x 6.5"

Circuit Pattern: Interleaved Bus/
Ground Plane
Contacts: 22/44 @ .156" Ctrs,
Ni/Gold
Width/Thick: 6.50"/.062"
Height: 4.50"
16-Pin DIP Capacity: 24
Material: CEM-1
Wire-Wrap Terminals: T44, T46, T49, T68
Wire-Wrap Socket Pins: R32
Solder Connector: R644
Extender: 3690
Rec. Card Cage: Series 13
Wire-Wrap Connector: R644-3
Hole Diameter: .042"

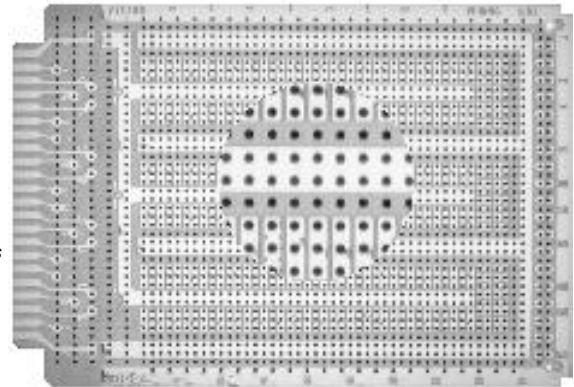
- Power bus in rows across component side; overall ground plane on wiring side
- 0.085" etched clearance area around each hole on ground plane side
- Bus and plane surfaces solder coated for user convenience
- To commit wire-wrap pins to ground planes, use Vector T124 solder washers, available separately
- Layout paper and instructions included
- Row and column legends provided



3677-2 4.5" x 6.5"

Circuit Pattern: 3-Hole Solder Pad
Contacts: 22/44 @ .156" Ctrs.
Ni/Gold
Width/Thick: 6.50"/.062"
Height: 4.50"
16-Pin DIP Capacity: 12
Material: CEM-1
Wire-Wrap Terminals: T44, T46, T49, T68
Wire-Wrap Socket Pins: R32
Solder Connector: R644
Extender: 3690
Rec. Card Cage: Series 13
Wire-Wrap Connector: R644-3
Hole Diameter: .042"

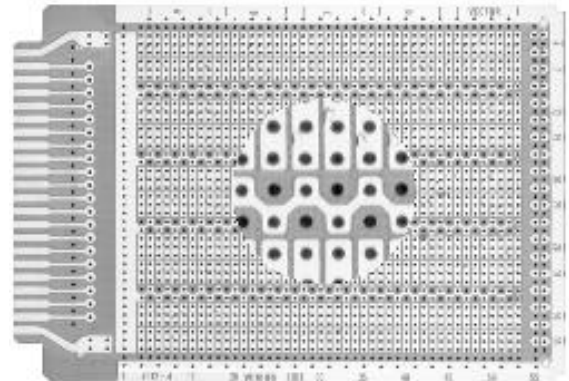
- 3-hole solder pads (0.28" x 0.080") for interconnecting multiple component leads
- Voltage/ground buses interleaved between pad areas on wiring side
- Row and column legends provided
- Test point area, with solder pads around holes, provided along back edge of board
- Layout paper and instructions included



4112-4 4.5" x 6.5"

Circuit Pattern: 3-Hole Solder Pad
Contacts: 22/44 @ .156" Ctrs,
Ni/Gold
Width/Thick: 6.50"/.062"
Height: 4.50"
16-Pin DIP Capacity: 25
Material: CEM-1
Wire-Wrap Terminals: T44, T46, T49, T68
Wire-Wrap Socket Pins: R32
Solder Connector: R644
Extender: 3690
Rec. Card Cage: Series 13
Wire-Wrap Connector: R644-3
Hole Diameter: .042"

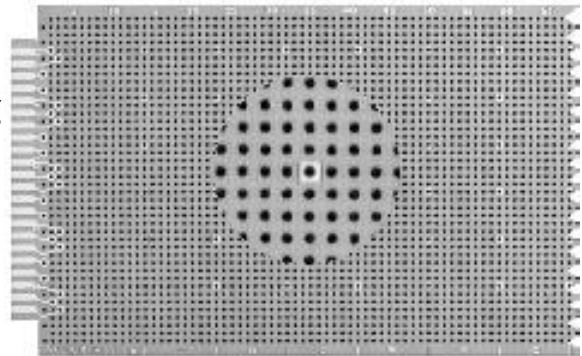
- Continuous ground plane on component side with 0.085" clearance pad around each hole
- 3-hole solder pads (0.28 x 0.080") for interconnecting multiple component leads
- Row and column legends provided
- Layout paper and instructions included

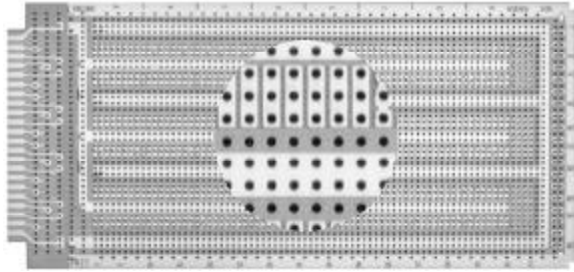


3662-2 4.5" x 9.6"

Circuit Pattern: Contacts Only
Contacts: 22/44 @ .156" Ctrs,
Ni/Gold
Width/Thick: 9.60"/.062"
Height: 4.50"
16-Pin DIP Capacity: 90
Material: CEM-1
Wire-Wrap Terminals: T44, T46, T49, T68
Wire-Wrap Socket Pins: R32
Solder Connector: R644
Extender: 3690-6
Rec. Card Cage: Series 14
Wire-Wrap Connector: R644-3
Hole Diameter: .042"

- Unrestricted component placement over entire board surface
- Row and column legends provided
- Layout paper and instructions included



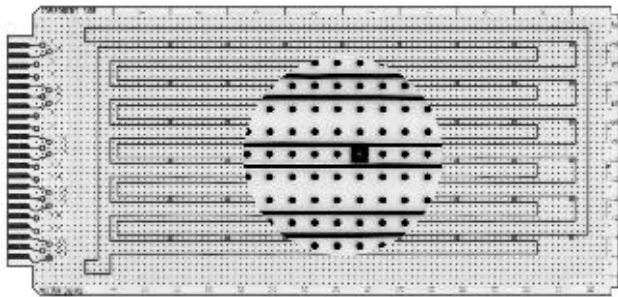


3677

Circuit Pattern: 3-Hole Solder Pad
Contacts: 22/44 @ .156" Ctrs., Ni/Gold
Width/Thick: 9.60"/.062"
Height: 4.50"
16-Pin DIP Capacity: 21
Material: CEM-1
Wire-Wrap Terminals: T44, T46, T49, T68
Wire-Wrap Socket Pins: R32
Solder Connector: R644
Extender: 3690
Rec. Card Cage: Series 14
Wire-Wrap Connector: R644-3
Hole Diameter: .042"

4.5" x 9.6"

- 3-hole solder pads (0.28" x 0.080") for interconnecting multiple component leads
- Row and column legends provided
- Layout paper and instructions included

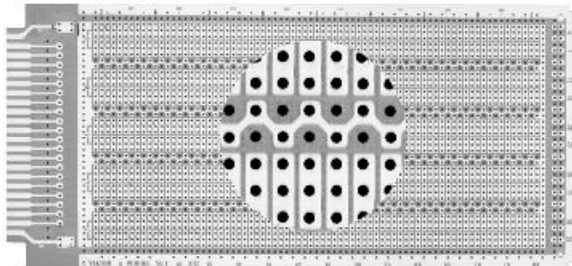


3682

Circuit Pattern: Interleaved Buses
Contacts: 22/44 @ .156 Ctrs., Ni/Gold
Width/Thick: 9.60"/.062"
Height: 4.50"
16-Pin DIP Capacity: 48
Material: CEM-1
Wire-Wrap Terminals: T44, T46, T49, T68
Wire-Wrap Socket Pins: R32
Solder Connector: R644
Extender: 3690-6
Rec. Card Cage: Series 13
Wire-Wrap Connector: R644-3
Hole Diameter: .042"

4.5" x 9.6"

- Etched bus pattern on wiring side, solder-coated for user convenience
- Bus outlines traced on component side
- Mounts DIPs with 0.3", 0.4" and 0.9" lead spacings
- Layout paper and instructions included
- Row and column legends provided



4112

Circuit Pattern: 3-Hole Solder Pad
Contacts: 22/44 @ .156" Ctrs., Ni/Gold
Width/Thick: 9.60"/.062"
Height: 4.50"
16-Pin DIP Capacity: 40
Material: FR4 Epoxy Glass
Wire-Wrap Terminals: T44, T46, T49, T68
Wire-Wrap Socket Pins: R32
Solder Connector: R644
Extender: 3690-6
Rec. Card Cage: Series 13
Wire-Wrap Connector: R644-3
Hole Diameter: .042"

4.5" x 9.6"

- Zig-zag bus pattern on wiring side provides access to voltage or ground at alternating hole positions
- 3-hole solder pads (0.28" x 0.080") for interconnecting multiple component leads
- Continuous ground plane on component side with 0.085" etched clearance area around each hole
- Layout paper and instructions included
- Row and column legends provided